

# **Enhancement Mode N-Channel Power MOSFET**

 $TO-252/NMOS/20V/\pm12V/0.9V/120A/2.2m\Omega$ 

Rev<sub>0.7</sub>





# 20V, $2.2m\Omega$ , 120A, N-Channel

#### 1.Features

- ◆ 20V MOSFET technology
- ◆ Low on-state resistance
- Fast switching
- ♦ Vgs±12V

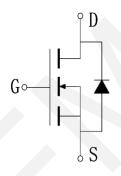
## 2.Applications

- ♦ Power Switching Application
- ◆ Load Switching



Pin Description

V <sub>DS</sub>	R <sub>DS(on)</sub> Typ.	I <sub>D</sub> Max.
20V	2.2mΩ @4.5V	1004
	3mΩ @ 2.5V	120A



Schematic Diagram

## 3. Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WP20H20K	WP20H20K	TO-252	2,500	25,000

## 4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units	
Drain to Source Voltage	V <sub>DSS</sub>	20	V	
Gate to Source Voltage	V <sub>GSS</sub>	±12	V	
Drain Current (DC)	ID	120	А	
Drain Current (Pulse), PW≤300μs	I <sub>DP</sub>	243	А	
Total Dissipation	P <sub>D</sub>	83	W	
Avalanche Energy, Single Pulsed	Eas	196	mJ	
Junction Temperature	Tj	150	°C	
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C	

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



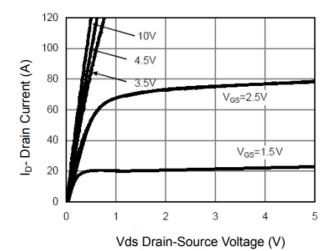
## 5.Electrical Characteristics at Ta=25 $^{\circ}\mathrm{C}$ (Note 2)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Drain to Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$I_D = 250 \mu A$ , $V_{GS} = 0 V$	20	24		V
Zero-Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V			1	μΑ
Gate to Source Leakage Current	I <sub>GSS1</sub>	$V_{GS} = \pm 12V, V_{SS} = 0V$			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250µA	0.5	0.9	1.2	V
Static Drain to Source On-State	В	I <sub>D</sub> =30A, V <sub>GS</sub> =4.5V	-	2.2	2.9	mΩ
Resistance	R <sub>DS(on)</sub>	I <sub>D</sub> =20A, V <sub>GS</sub> = 2.5V	-	3	4	mΩ
Input Capacitance	Ciss	V <sub>GS</sub> =0V,		2016		pF
Output Capacitance	Coss	V <sub>DS</sub> =10V,		391		pF
Reverse Transfer Capacitance	Crss	Frequency=1.0MHz		130		pF
Turn-on Delay Time	t <sub>d(on)</sub>			6		ns
Rise Time	<b>t</b> r	$V_{DD} = 10V, I_D = 30A,$		4		ns
Turn-off Delay Time	t <sub>d(off)</sub>	$V_{GS} = 10V$ , $R_{GEN} = 2.7\Omega$		31		ns
Fall Time	t <sub>f</sub>			5		ns
	Qg	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 4.5V,		15		nC
Total Gate Charge	Qgs			3		nC
	Q <sub>gd</sub>	I <sub>D</sub> = 30A		4		nC
Diode Forward Voltage	V <sub>FSD</sub>	I <sub>S</sub> = 30A, V <sub>GS</sub> = 0		0.8	1.2	V

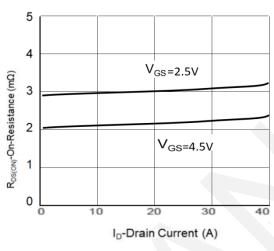
Note 2: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



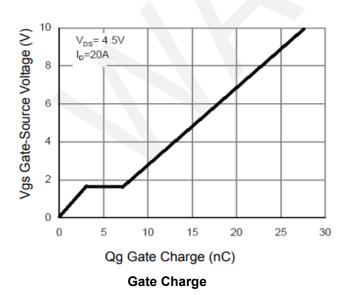
## 6. Typical electrical and thermal characteristics

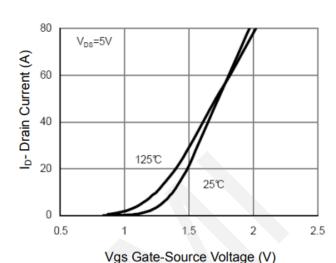


### **Output Characteristics**

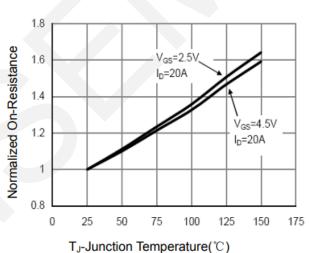


#### **Rdson-Drain Current**

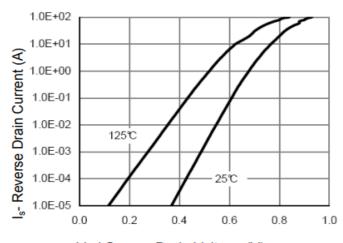




**Transfer Characteristics** 



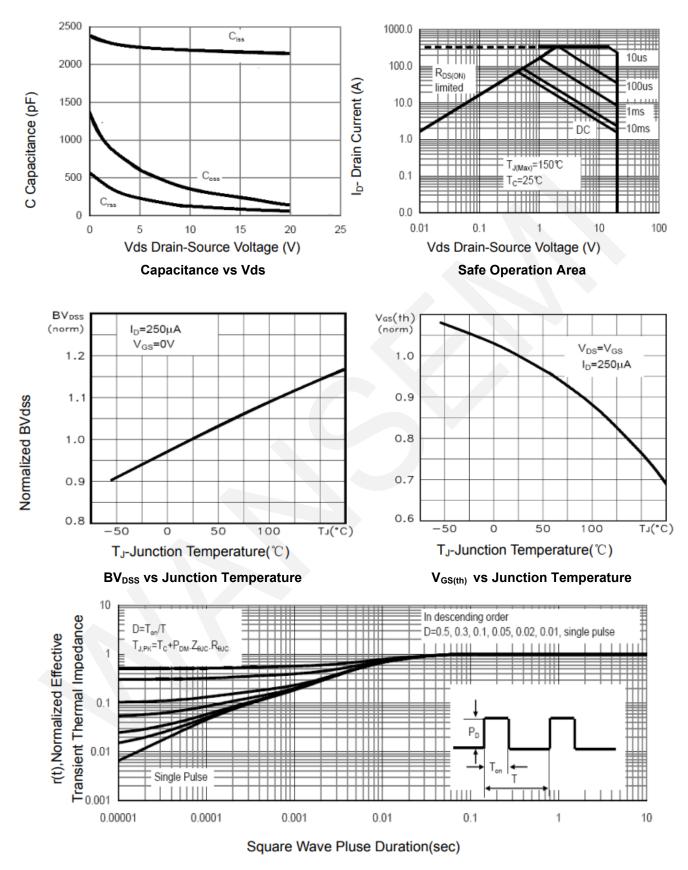
**Rdson-Junction Temperature** 



Vsd Source-Drain Voltage (V)

Source-Drain Diode Forward

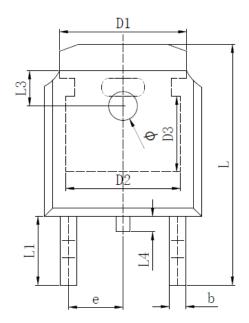


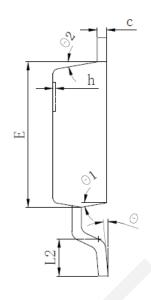


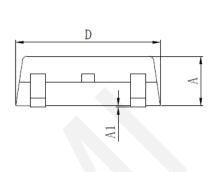
**Normalized Maximum Transient Thermal Impedance** 



# 7.Package Dimensions







SYMBOL	MILLIMETER			
	MIN	Тур.	MAX	
A	2. 200	2. 300	2. 400	
A1	0.000		0. 127	
b	0. 640	0.690	0.740	
c(电镀后)	0. 460	0. 520	0. 580	
D	6. 500	6. 600	6. 700	
D1	5. 334 REF			
D2	4.826 REF			
D3	3.166 REF			
E	6. 000	6. 100	6. 200	
е	2.286 TYP			
h	0.000	0. 100	0. 200	
L	9. 900	10. 100	10. 300	
L1	2.888 REF			
L2	1. 400	1. 550	1. 700	
L3	1.600 REF			
L4	0.600	0.800	1.000	
ф	1. 100	1. 200	1. 300	
θ	0°		8°	
θ1	9° TYP			
θ2	9° TYP			



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